



NSAI
Standards

Irish Standard
I.S. EN 61191-3:2017

Printed board assemblies - Part 3: Sectional specification - Requirements for through-hole mount soldered assemblies

I.S. EN 61191-3:2017

Incorporating amendments/corrigenda/National Annexes issued since publication:

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This document is based on:

EN 61191-3:2017

Published:

2017-09-01

This document was published under the authority of the NSAI and comes into effect on:

2017-09-19

ICS number:

31.240

NOTE: If blank see CEN/CENELEC cover page

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National Foreword

I.S. EN 61191-3:2017 is the adopted Irish version of the European Document EN 61191-3:2017, Printed board assemblies - Part 3: Sectional specification - Requirements for through-hole mount soldered assemblies

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EUROPEAN STANDARD

EN 61191-3

NORME EUROPÉENNE

EUROPÄISCHE NORM

September 2017

ICS 31.240

Supersedes EN 61191-3:1998

English Version

**Printed board assemblies - Part 3: Sectional specification -
Requirements for through-hole mount soldered assemblies
(IEC 61191-3:2017)**

Ensembles de cartes imprimées - Partie 3: Spécification
intermédiaire - Exigences relatives à l'assemblage par
brasage de trous traversants
(IEC 61191-3:2017)

Elektronikaufbauten auf Leiterplatten - Teil 3:
Rahmenspezifikation - Anforderungen an gelötete
Baugruppen in Durchsteckmontage
(IEC 61191-3:2017)

This European Standard was approved by CENELEC on 2017-07-04. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

EN 61191-3:2017**European foreword**

The text of document 91/1375/CDV, future edition 2 of IEC 61191-3, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61191-3:2017.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2018-04-04
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2020-07-04

This document supersedes EN 61191-3:1998.

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In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60068-2-20	NOTE	Harmonized as EN 60068-2-20.
IEC 60068-2-58	NOTE	Harmonized as EN 60068-2-58.
IEC 61188-5-1	NOTE	Harmonized as EN 61188-5-1.
IEC 61188-5-2	NOTE	Harmonized as EN 61188-5-2.
IEC 61188-5-3	NOTE	Harmonized as EN 61188-5-3.
IEC 61188-5-4	NOTE	Harmonized as EN 61188-5-4.
IEC 61188-5-6	NOTE	Harmonized as EN 61188-5-5.
IEC 61188-7	NOTE	Harmonized as EN 61188-7.
IEC 61189-2	NOTE	Harmonized as EN 61189-2.
IEC 61190-1-2	NOTE	Harmonized as EN 61190-1-2.
IEC 61193-1	NOTE	Harmonized as EN 61193-1.
IEC 61193-3	NOTE	Harmonized as EN 61193-3.
IEC 62326-1	NOTE	Harmonized as EN 62326-1.
IEC 62326-4	NOTE	Harmonized as EN 62326-4.

IEC 62326-4-1

NOTE Harmonized as EN 62326-4-1.

ISO 9001

NOTE Harmonized as EN ISO 9001.

EN 61191-3:2017

Annex ZA
(normative)**Normative references to international publications
with their corresponding European publications**

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194	-	Printed board design, manufacture and assembly - Terms and definitions	-	-
IEC 61191-1	2013	Printed board assemblies -- Part 1: Generic specification - Requirements for soldered electrical and electronic assemblies using surface mount and related assembly technologies	EN 61191-1	2013
IPC-A-610	-	Acceptability of Electronics Assemblies	-	-



IEC 61191-3

Edition 2.0 2017-05

INTERNATIONAL STANDARD

**Printed board assemblies –
Part 3: Sectional specification – Requirements for through-hole mount soldered
assemblies**





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IEC 61191-3

Edition 2.0 2017-05

INTERNATIONAL STANDARD

**Printed board assemblies –
Part 3: Sectional specification – Requirements for through-hole mount soldered
assemblies**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

ICS 31.240

ISBN 978-2-8322-4397-8

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

PRINTED BOARD ASSEMBLIES –

Part 3: Sectional specification – Requirements for through-hole mount soldered assemblies

FOREWORD

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International Standard IEC 61191-3 has been prepared by WG 2: Requirements for electronics assemblies, of IEC technical committee 91: Electronics assembly technology.

This second edition cancels and replaces the first edition published in 1998. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) The requirements have been updated to be compliant with the acceptance criteria in IPC-A-610F.

The text of this standard is based on the following documents:

CDV	Report on voting
91/1375/CDV	91/1435/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61191 series, published under the general title *Printed board assemblies*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

PRINTED BOARD ASSEMBLIES –

Part 3: Sectional specification – Requirements for through-hole mount soldered assemblies

1 Scope

This part of IEC 61191 prescribes requirements for lead and hole solder assemblies. The requirements pertain to those assemblies that totally use through-hole mounting technology (THT), or the THT portions of those assemblies that include other related technologies (i.e. surface mount, chip mounting, terminal mounting).

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

IEC 61191-1:2013, *Printed board assemblies – Part 1: Generic specification – Requirements for soldered electrical and electronic assemblies using surface mount and related assembly technologies*

IPC-A-610, *Acceptability of Electronic Assemblies*

3 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 60194 apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

3.1

THT

through-hole technology

technology that permits an electrical connection of components to a conductive pattern by the use of plated or non-plated holes with annular rings in the mounting substrate

4 General requirements

Requirements of IEC 61191-1 are a mandatory part of this specification. Workmanship shall meet the requirements of IPC-A-610 in accordance with the classification requirements of this document.

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